

Device Material Content

5555 NE Moore Ct. Assembly: ASEM Package Code: Hillsboro OR 97124 Size (mm): 17 x 17 custreq@latticesemi.com Package: 332 caBGA **BG332** Lead pitch (mm): 0.8 **Total Device Weight** 1.04 Grams **Products:** MSL: 3 June, 2022 XO2 Reflow max (°C): 260 % of Total % of Total Weight (g) Weight (g) CAS# Substance % of Subst. Notes / Assumptions: Pkg. Wt. Pkg. Wt. Die 0.72% 0.0075 Die size: 4.41 x 4.36 mm 0.72% 0.0075 Silicon chip 7440-21-3 100.00% 45.53% 0.4735 Mold Compound Mold Compound: Sumitomo G750SE (ULA) 2.28% 0.0237 Epoxy Resin A 5.00% 0.68% 0.0071 Epoxy Resin B 1.50% 2.28% 0.0237 Phenol Novolac 9003-35-4 5.00% 2.28% 0.0237 Metal Hydroxide 5.00% Carbon Black 0.14% 0.0014 1333-86-4 0.30% 37.88% 0.3939 Silica Fused 60676-86-0 83.20% D/A Epoxy 0.10% 0.0011 Die attach epoxy: Henkel (Ablebond) 2100A 7440-22-4 0.08% 0.00085 Silver 80.00% 0.02% 0.00021 Esters & resins 20.00% Wire 0.42% 0.0044 0.8 mil diameter; 1 wire per solder ball 0.42% 98.50% 0.0043 Copper 7440-50-8 1.50% 0.01% 0.0001 Palladium 7440-05-3 Solder Balls 11.32% 0.1177 SAC305 10.92% 0.1136 Tin (Sn) 7440-31-5 96.50% 0.34% 0.0035 Silver (Ag) 7440-22-4 3.00% 0.06% 0.0006 7440-50-8 0.50% Copper (Cu) Substrate 19.16% 0.1992 BT Resin CCL-HL832NX-A 13.03% 0.1355 Glass fiber 65997-17-3 68.00% 6.13% 0.0638 BT Resins 32.00% Foil 13.97% 0.1453 11.90% 0.1237 Copper 7440-50-8 85.15% 1.99% 0.0207 Nickel 7440-02-0 14.28% 0.08% Gold 7440-57-5 0.57% 0.0008 Solder Mask 8.78% 0.0913 Solder mask PSR4000 AUS 308 4.93% 0.0513 Quartz 14808-60-7 56.20% 1.40% 0.0146 3-methoxy-3-methylbutylacetate 103429-90-9 16.00% 22.00%

Barium Sulfate

Talc (containing no asbestiform fibers)

Trade secret ingredients

7727-43-7

14807-96-6

3.00%

2.80%

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0.0201

0.0027

0.0026

1.93%

0.26%

0.25%







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